



Material Content Data Sheet



Sales Product Name		ICE3AR10080JZ		Issued		1. August 2018		
MA#		MA001064176						
Package		PG-DIP-7-3		Weight*		645.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.159	0.64	0.64	6444	6444
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		5999	
wire	non noble metal	copper	7440-50-8	157.218	24.36	25.00	243594	249968
	noble metal	gold	7440-57-5	0.394	0.06	0.06	611	611
	encapsulation	organic material	carbon black	1333-86-4	2.345	0.36		3633
encapsulation	plastics	epoxy resin	-	63.311	9.81		98094	
	inorganic material	silicondioxide	60676-86-0	403.314	62.49	72.66	624896	726623
leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10008	10008
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2470	2470
glue	plastics	epoxy resin	-	0.438	0.07		678	
	noble metal	silver	7440-22-4	2.064	0.32	0.39	3198	3876
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com